

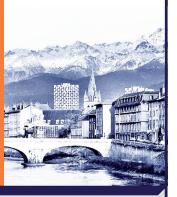


2013 International Semiconductor Conference Dresden - Grenoble (ISCDG)

alternating venue in Dresden (Germany) and Grenoble (France) every other year

Technology, Design, Packaging, Simulation and Test International Conference, Short Course and Table Top Exhibition

September, 26 - 27, 2013 - Dresden, Germany



"Meet Leading Players and Experts at the ISCDG 2013 in Dresden, Germany". The Largest Microelectronic Center in Europe!

Grenoble and Dresden are the two major European Semiconductor Research, Development and Production sites. In the preceding editions of 2009 and 2011, the conference was named "Semiconductor Conference Dresden". The objective of the ISCDG is to enhance the visibility of international excellence of the European players. The first edition of ISCDG was held in 2012 in Grenoble. The 2013 ISCDG will be held in Dresden. The venue will be alternating in Dresden and Grenoble every other year.

Call for Papers

Main areas covered by the conference: Materials, devices and systems science, engineering and architectures and their characterization available soon

Papers are requested in the following areas:

Integrated Circuit and System Design

Mixed-signal, analog and digital circuits and systems for high speed and/or low power consumption, adaptive power management, RF up to sub-THz, low costs, and advanced performance and density, circuits in More than Moore and Beyond Moore technologies. Manufacturing challenges (cost and cycle time reduction, test, wafer-prime-production etc.), ...

• More Moore and Beyond Moore Devices Technologies and Architectures

Ultimate CMOS (silicon and IV-IV strained alloys on insulator, multi-gate and channel transistors, III-V channels), nanowires, thin films dielectrics: high-k and low-k; nano-materials; advanced on-chip interconnects; Beyond Moore: TunFETs, carbon electronics....

Memory Technologies

Stand alone and Embedded Memory Technologies, new memory technologies: RRAMs, CBRAMs, MRAMs, 1T DRAM, ...

• More than Moore Technologies

MEMS, NEMS, power devices, RF and analog passive components (MIM, filters, supercapacitors, inductances,...), spintronics based devices, bio sensors, imagers, thermoelectric, energy harvesting, ...

• Interconnection and Packaging Technologies

3D and novel interconnects, wire bonding, flip chip, solder replacement flip chip, under bump metallurgy, high density substrates, New packaging technologies for single chip, multi-chip, wafer level, power and stacked-die packages, wafer bumping and thinning, ...

• Optical Devices and Photonics

Optical component assemblies, electro-optical modules, waveguides, silicon based photonic devices, organic devices, optical materials, ...

Organic and Flexible Electronics

Polymer and organic, printed electronics, organic PV and PV in organic, OLEDs, ...

• Characterization, Quality and Reliability

Electrical characterization, testing strategies and protocols, physical characterization for process development and process control, component, board and system level reliability assessment, failure analysis, interfacial adhesion, accelerated testing and models, component and system qualification.

Modeling and Simulation

EDA, TCAD, electrical, thermal, thermo-mechanical, reliability, optical, modeling and simulation for devices, component and system level applications, ...



CALL FOR PAPERS





2013 International Semiconductor Conference Dresden - Grenoble (ISCDG)

alternating venue in Dresden (Germany) and Grenoble (France) every other year

Technology, Design, Packaging, Simulation and Test International Conference, Short Course and Table Top Exhibition

September, 26 - 27, 2013 - Dresden, Germany



June 09, 2013

Key Dates:

Paper submission deadline

Paper acceptance

Deadline for early bird registration

(accomodation, conference and short course fees)

April 30, 2013

June 15, 2013

August 15, 2013

Submit Paper

Submission of papers in the areas mentioned above are encouraged and solicited to describe original work.

The paper must include the purpose, applications, results, comparison with the state-of-the-art, conclusions, visualizing pictures and key references.

All conference papers will be included in IEEEXplore.

Papers will be presented at the conference as talks or posters.

>> Please send your proposal to paper-iscdg@gerotron.com

Guidelines for submitted papers:

- Papers have to be formatted in accordance with the <u>IEEE Manuscript Templates for Conference Proceedings</u>
- · Contributions can only be accepted in English language
- Paper length: min. one page with text, second page with figures.
 - After conformation of acceptance 3 4 pages for the IEEE explorer
- File format: pdf, file size max. 5 MB

In addition we need the ISCDG Paper Submission Form



http://iscdg.org/ISCDG_2013_paper_submission_form.doc

Please fill out the form below and send this document together with your paper submission to us.

>> Official website: www.iscdg.org

General Management & Publicity:

GEROTRON Communication GmbH

Contact: Georg Schmidt

Bunsenstr. 5/II 82152 Martinsried, Germany E-mail: georg.schmidt@gerotron.com Phone: +49 (0)89 189 08 17 80 Fax: +49 (0)89 89 55 69 29 www.gerotron.com

Co-Management:

INSIGHT OUTSIDE

Phone: +33 (0)4 38 38 18 22 / +33 (0)6 10 80 31 98

Fax: +33 4 38 38 18 19

E-mail: iscdg2o12@insight-outside. fr

www.insight-outside.fr



CALL FOR PAPERS



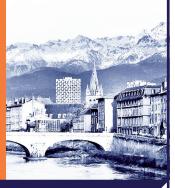


2013 International Semiconductor Conference Dresden - Grenoble (ISCDG)

alternating venue in Dresden (Germany) and Grenoble (France) every other year

Technology, Design, Packaging, Simulation and Test International Conference, Short Course and Table Top Exhibition

September, 26 - 27, 2013 - Dresden, Germany



supported by



















Patronage



Hermann Eul
General Manager
Intel Mobile and Communications Group;
Intel Corporate Vice President, Santa Clara, USA

Steering Committee

General Chair

Thomas Gessner, Fraunhofer ENAS

General Co-Chair

Simon Deleonibus, CEA LETI Joachim Burghartz, IMS CHIPS

Technical Program Chair

Christoph Kutter, Fraunhofer EMFT

Technical Program Co-Chair

Lothar Pfitzner, Fraunhofer IISB **Gérard Ghibaudo**, Grenoble INP

Advisors at Large

Frank Ellinger, TU Dresden **Robert Weigel**, University of Erlangen-Nuremberg

Publications Chair

Dietmar Kissinger, University of Erlangen-Nuremberg

Publications Co-Chair

Francis Balestra, Sinano Institute / Grenoble INP

General Exhibition Chair

Georg Schmidt, GEROTRON COMMUNICATION

Members of the Technical Program Committee

Hans-Joachim Barth, Intel Mobile Communications

Marc Belleville, CEA LETI

Francois Bertin, CEA LETI

Jumana Boussey, CNRS

Jean Emmanuel Broquin, Grenoble INP

Andreas Bruening, ZMDI

Isabelle Chartier, LITEN

Renaud Demadrille, INAC

Philippe Ferrari, UJF

Gerhard Fettweis, TU Dresden

Norbert Fruehauf, University of Stuttgart

Herve Jaouen, STMicroelectronics

Anne Kaminski-Cachopo, Grenoble INP

Klaus-Dieter Lang, Fraunhofer IZM

Paolo Lugli, TU Munich

Linus Maurer, Universität der Bundeswehr Munich

Bernd Meinerzhagen, TU Braunschweig

Bernd Michel, Fraunhofer ENAS

Slobodan Mijalkovic, SILVACO

Stephane Monfray, STMicroelectronics

Dominique Morche, CEA LETI

Bich Yen Nguyen, SOITEC

Lucian Prejbeanu, CEA LETI

Quentin Rafhay, Grenoble INP

Stefan Schulz, Fraunhofer ENAS

Solon Spiegel, Rio Systems

Roland Thewes, TU Berlin

Norbert Thyssen, Infineon

Claude Vauchier, CEA LETI

Paul Yu, UCSD

Ehrenfried Zschech, Fraunhofer IZFP



CALL FOR PAPERS